

SECOND RESUBMITTAL PER E-MAIL 8/28/00.

BJT/9/6/00

CONTRACT C WORKSHEET

PRON P10RCCX1

AMC 1

AMSC G

ATC CTRRE

TDP 12951116

TDPL DATE 08/18/00

NSN 5998013404467

NOMENCLATURE CIRCUIT CARD

ENGINEERING EXCEPTIONS: The following engineering changes apply to
this procurement action(s):

The following are the current addresses for Vendors depicted in
the TDP:

DN2 North American Philips is; Philips Semiconductors, Philips
Electronics Sunnyvale CA 94088-3409

DN4 NDK America Inc Fremont CA 94539

ITT Cannon Santa Ana CA 92705

INTEL CORP Santa Clara CA 95051

Integrated Device Technology INC Santa Clara CA 95054-3090

DN6 FCI Electronics USA York PA 17402

DN7 MIL-I-43553 is replaced with CID A-A-56032

MIL-P-81728 is replaced with SAE-AMS-P-81728.

DN8 QQ-S-571 is replaced with J-STD-006.

DN 9 Missing drawing 12951177 is replaced with
drawing 12951180.

Missing drawing 12951178 is replaced with
drawing 12951179.

DN 11 Add Alternative Part:AM27C64-150DC Advanced Micro

Devices[4-

DND MIL-STD-2000 is replaced with Solder Statement below

DN5 Integrated Device item is available.

dDN1 Harris Corp is replaced with Intersill

DN3 "Texas Instrument " part No. are correct.

All soldering and soldering related operations shall be performed in accordance with a detailed soldering process plan to be developed and maintained by the contractor. The plan shall include the procedures to be used for all soldering and soldering related operations (i.e. hand soldering, tinning, solderability testing or verification, automated soldering, inspection, process controls). Each procedure shall describe the operation in sufficient detail to ensure that the performance requirements for the item being manufactured are met. As a minimum, each procedure shall include the process, tools, equipment, materials and acceptance criteria used for the operation. The soldering process plan shall be made available to the cognizant government technical agency.

In lieu of developing a soldering process plan, the contractor may elect to utilize ANSI/IPC/J-STD-001, Class 3*, with the cleanliness designator as indicated below:

Flux Type in use	Cleanliness Designator**
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Low Residue/No Clean Flux	C02
Rosin Based Flux	C22
Water Soluble Flux	C22

***Class 3 High Performance Electronic Products**

Includes equipment for commercial and military products where performance or performance-on-demand is critical. Equipment cannot be tolerated, end-item use may be uncommonly harsh, and the equipment must function when required, such as life support systems and critical weapons systems.

**ANSI/IPC/J-STD-001 Rev A, paragraph 8.3.2 and sub-paragraphs.

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NOMENCLATURE CIRCUIT CARD

DOCUMENT 12951142

DELETE

ADD

REV ORIGINAL

REV A 2 sht's

DN 11: Add alternative part: AM27C64-150DC Advanced Micro Devices

Oldsmar, FL 34677

(IHS)

DN 12: Add alternative part: P8742AH intel Corp

Santa Clara Ca 95051

(IHS)

GFM/GFE: DRAWING NO.

MYLARS REQUIRED (Check one): X Y or N